

SMT ADHESIVE - Heat Cure Type

JU - 41P & JU - 44P

■ Features

- Ensures excellent printing with high dot profile.
- High slump resistance.
- Very high bonding strength.
- Long shelf life.

Before curing	Application		Printing	
	Products		JU-41P	JU-44P
	Composition		Epoxy	
	State • Color		Paste • Red	
	Specific gravity		1.22 ± 0.05	1.26 ± 0.05
	Viscosity (Pa.s • 30°C)		100 ± 10	82 ± 5
	Thixotropy (30°C)		3.5 ± 0.5	5.5 ± 0.5
	Non-volatile (105°C • 3 hr)		> 99%	> 99%
	Viscosity variation rate (105°C, 20 hrs)		5%	5%
	Shelf life	At room temp. (20°C)		3 months
Below 10°C		6 months		
After curing	State • Color		Polymer, dark red	
	Bonding strength	2125 square chip	> 3 kg	> 3 kg
		Minimold Tr	> 3 kg	> 3 kg
	Copper plate corrosion (40°C 90%RH72hr)		Passed	Passed
	Heat resistivity (250°C × 10sec.)		Passed	Passed
	Surface insulation resistant	Initial value (Ω)	> 1 × 10 ¹²	> 1 × 10 ¹²
		40°C, 95%RH × 96hr(Ω)	> 1 × 10 ¹¹	> 1 × 10 ¹¹
	Water absorption		0.1%	0.1%
	Dielectric constant (1 MHz)		3.4	3.7
Dielectric tangent (1 MHz)		0.016	0.017	

Curing condition : 120°C × > 90sec.
 130°C ~ 150°C × > 60sec.

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